

<b>PCN Number:</b>	20190107002.0	<b>PCN Date:</b>	January 08, 2019
<b>Title:</b>	Datasheet for TMP102-Q1		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

### Notification Details

#### Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



**TMP102-Q1**

SBOS702D – OCTOBER 2014 – REVISED DECEMBER 2018

Changes from Revision C (December 2015) to Revision D	Page
• Changed the supply voltage maximum value from: 3.6 V to: 4 V .....	4
• Updated junction-to-ambient thermal resistance from 200°C/W to 210.3°C/W .....	5
• Updated junction-to-case (top) thermal resistance from 73.7°C/W to 105.0°C/W .....	5
• Updated junction-to-board thermal resistance from 34.4°C/W to 87.5°C/W .....	5
• Updated junction-to-top characterization parameter from 3.1°C/W to 6.1°C/W .....	5
• Updated junction-to-board characterization parameter from 34.2°C/W to 87.0°C/W .....	5
• Added the <i>Receiving Notification of Documentation Updates</i> section .....	24

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP102-Q1	SBOS702C	SBOS702D

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TMP102-Q1>

#### Reason for Change:

To accurately reflect device characteristics.

#### Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

#### Changes to product identification resulting from this PCN:

None.

#### Product Affected:

TMP102AQDRLRQ1			
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>